

Gate Driver Module 2DMB80407CC

■Overview

Gate driver 2DMBxxxxxCC is a dual channel gate driver designed for IGBT and SiC MOSFET.

The high breakdown voltage and low parasitic capacitance make it suitable for gate drives such as SiC MOSFET and IGBT.

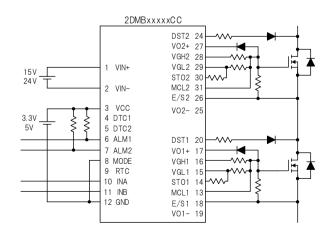
Features

- ·Ideal for drive of IGBT and SiC MOSFET
- •Gate voltage : +18V/-4V
- ·ALL-IN-ONE (Built-in isolated DC / DC converter and gate drive circuit)
- ·Low parasitic capacitance (about 12pF); highly resistant to common-mode noise.
- Fast response : about 100nsec(typ)
- •The isolation for primary-secondary signal used fast response isolator.
- ·Input-to-Output dielectric withstand voltage : AC5000V
- ·Output CH1-to-Ouput CH2 dielectric withstand voltage : AC4000V
- ·Input-to-Output insulation distance : 14mm (clearance · creepage)
- ·Output CH1-to-Output CH2 insulation distance : 7mm (clearance), 12mm(creepage)
- ·DC/DC converter input voltage :13~28V
- ·Signal input voltage : 3.3V,5V
- •Overload protection (DC/DC converter)
- •Overheat protection (DC/DC converter)
- ·Half bridge mode (Gate drive circuit)
- ·Desaturation protection (Gate drive circuit)
- $\cdot \, \text{Soft}$ turn-off function (Gate drive circuit)
- ·Fault signal output function (Gate drive circuit)
- ·Miller clamp function (Gate drive circuit)
- ·Under-voltage lockout(UVLO) (Gate drive circuit)
- ·Safety standards:UL508(file no.E243511) (DC/DC converter only)
- ·Reinforced isolation according to IEC 60664-1 (IEC61800-5-1, IEC62477-1, IEC62109-1, etc.)
- ·UL compliant (UL1741, UL508, etc.)

Application

Industrial inverter, power conditioner, etc …

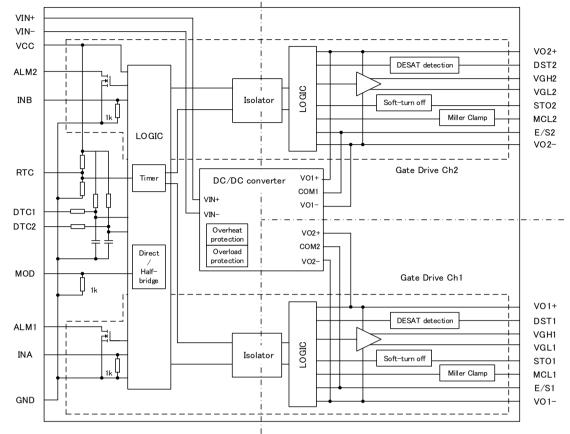
■Circuit Image





2DMB80407CC Datasheet

■Internal Block Diagram



■Pin Connection

Inn	11t -
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input			
Pin No.	Name	CH	Function
1	VIN+	Common	Power supply for DC/DC converter(+)
2	VIN-	Common	Power supply for DC/DC converter(-)
3	VCC	-	Power supply for drive circuit
4	DTC1	1	Dead time adjustment
5	DTC2	2	Dead time adjustment
6	ALM1	1	Alarm signal output
7	ALM2	2	Alarm signal output
8	MOD	-	Mode select
9	RTC	-	Recovery time of protection circuit con
10	INA	1	Control input A
11	INB	2	Control input B
12	GND	-	Ground for drive circuit

Outpu	t		
Pin No.	Name	CH	Function
13	MCL1	1	Miller clamp pin
14	ST01	1	Soft turn off pin
15	VGL1	1	Gate OFF side pin
16	VGH1	1	Gate ON side pin
17	V01+	1	DC/DC converter output pin
18	E/S1	1	Emitter · source connection pin
19	V01-	1	DC/DC converter output pin
20	DST1	1	Desaturation protection pin
21	NONE	-	None
22	NONE	-	None
23	NONE	-	None
24	DST2	2	Desaturation protection pin
25	V02-	2	DC/DC converter output pin
26	E/S2	2	Emitter · source connection pin
27	V02+	2	DC/DC converter output pin
28	VGH2	2	Gate ON side pin
29	VGL2	2	Gate OFF side pin
30	STO2	2	Soft turn off pin
31	MCL2	2	Miller clamp pin



■I/O Condition Table

No.	Status			Inp	out			Output(CH2)					Output(CH1)				
INO.	Status	V0+	DST2	DST1	MOD	INB	INA	ALM2	VGH2	VGL2	ST02	MLC2	ALM1	VGH1	VGL1	ST01	MLC1
1	VOx+ UVLO	UVLO	Х	Х	Х	Х	Х	L	Hi-Z	Hi-Z	L	L	L	Hi-Z	Hi-Z	L	L
4	Normal	0	Х	L	L	Х	L	Х	Х	Х	Х	Х	Hi-Z	Hi-Z	L	L	L
5	operation	0	Х	L	L	Х	Н	Х	Х	Х	Х	Х	Hi-Z	Н	Hi-Z	Hi-Z	Hi-Z
2	(Direct Mode)	0	L	Х	L	L	Х	Hi-Z	Hi-Z	L	L	L	Х	Х	Х	Х	Х
3	Widde/	0	L	Х	L	Н	Х	Hi-Z	Н	Hi-Z	Hi-Z	Hi-Z	Х	Х	Х	Х	Х
6	Normal	0	L	L	Н	L	Х	Hi-Z	Hi-Z	L	L	L	Hi-Z	Hi-Z	L	L	L
7	operation (Half-bridge	0	L	L	Н	Н	L	Hi-Z	Н	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	L	L	L
8	Mode)	0	L	L	Н	Н	Н	Hi-Z	Hi-Z	L	L	L	Hi-Z	Н	Hi-Z	Hi-Z	Hi-Z
9		0	L	Hi-Z	L	Х	L	Hi-Z	Х	Х	Х	Х	Hi-Z	Hi-Z	L	L	L
10	Desaturation	0	L	Hi-Z	L	Х	Η	Hi-Z	Х	Х	Х	Х	L	Hi-Z	Hi-Z	L	L
11	protection1	0	L	Hi-Z	Н	Н	L	Hi-Z	Н	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	L	L	L
12		0	L	Hi-Z	Н	Н	Н	Hi-Z	Hi-Z	L	L	L	L	Hi-Z	Hi-Z	L	L
13		0	Hi-Z	L	L	L	Х	Hi-Z	Hi-Z	L	L	L	Hi-Z	Х	Х	Х	Х
14	Desaturation	0	Hi-Z	L	L	Н	Х	L	Hi-Z	Hi–Z	L	L	Hi-Z	Х	Х	Х	Х
15	protection2	0	Hi-Z	L	Н	Н	L	L	Hi-Z	Hi-Z	L	L	Hi-Z	Hi-Z	L	L	L
16		0	Hi-Z	L	Н	Н	Н	Hi-Z	Hi-Z	L	L	L	Hi-Z	Н	Hi-Z	Hi-Z	Hi-Z

O : Vox+ UVLO > UVLO, X : Don't care



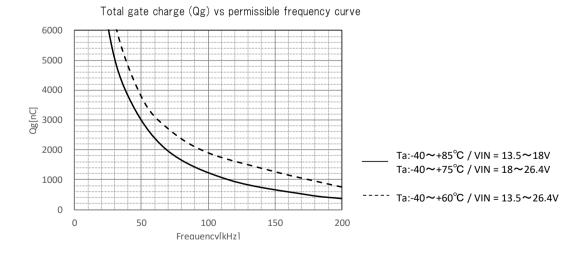
■Absolute Maximum Ratings

ltem	ltem		Min	Max	Unit	Conditions · Note
Input voltage for DC/DC co	nverter	V _{IN}	-0.3	28	Vdc	Between VIN+ to VIN-
Input-side signal voltage		$V_{CC,}V_{SG}$	-0.3	5.5	V	VCC, RTC, MOD, INA, INB
input-side signal voltage		V_{ALM}	-0.3	28	V	ALM1, ALM2
Input-side signal maximum o	current	I _{ALM}	-	5	mA	ALM1, ALM2
DESAT pin input voltage		V_{DESAT}	-0.3	V_{GH} +0.3	V	
Miller clamp pin input voltage	er clamp pin input voltage		V_{GL} -0.3	V_{GH} +0.3	V	
Maximum gate current	aximum gate current		-	43	А	
DC/DC converter output pc	ower	P _{OUT}	-	3.5	W	Per output circuit
Switching frequency		F _{sw}	-	200	kHz	See the permissible frequency curve
Operating temperature range	V _{IN} =13.5−18V	T _{OP}	-40	85	°C	See the permissible frequency curve
V _{IN} =18-26.4V		Τ _{ΟΡ}	-40	75	°C	See the permissible frequency curve
Operating humidity		RH _{OP}	20	95	%RH	No condensation
Storage temperature range		T _{STG}	-40	90	°C	
Storage humidity		RH_{STG}	5	95	%RH	No condensation

■Recommended Operating Conditions

ltem	Symbol	Min	Max	Unit	Conditions · Note
Input voltage range for DC/DC converter	V _{IN}	13.5	26.4	Vdc	
Input-side signal voltage range	$V_{CC,}V_{SG}$	3	5.5	Vdc	
Driver circuit number	Ν	-	2	-	
Logic high level input voltage	V_{SGH}	$V_{CC} imes 0.7$	-	V	MOD, INA, INB
Logic low level input voltage	V_{SGL}	-	$V_{\text{CC}} imes 0.3$	V	MOD, INA, INB
Source current of control signal	I _{SG}	5	-	mA	MOD, INA, INB V _{SG} =5V
Maximum gate drive capability (200 kHz)	Q _{MAX}	-	370	nC	Gate current (ave) = 74mA Reference value
Maximum gate drive capability (30 kHz)	Q _{MAX}	-	5000	nC	Gate current (ave) = 150mA Reference value
Maximum gate charge amount	Q_{G}	-	6000	nC	
Minimum input pulse width	t _{INMSK}	60	-	ns	

■Permissible frequency curve





	ltem	Symbol	Min	Тур	Max	Unit	Conditions · Note
DC/DC conve	erter						-
Start-up volta	age	V _{START}	-	-	13	V	
Input current		I _{IN}	-	0.45	-	А	Fsw=25kHz / Test load: 280nF
Standby powe	er	P _{STBY}	-	1.3	-	W	No load
Logic inputs							
Logic high lev	el input voltage	V_{SGH}	$V_{\text{CC}} \ x0.7$	-	-	V	MOD, INA, INB / Guaranteed by design
Logic low level input voltage		V _{SGL}	-	-	$V_{\text{CC}} imes 0.3$	V	MOD, INA, INB $/$ Guaranteed by design
Logic pull-down resistance		R_{SGD}	-	1000	-	Ω	MOD, INA, INB
Gate driver o	utput						
Gate ON side pi	in / output voltage(+)	V_{GH}, V_{O+}	17	18	19	V	No load
Gate OFF side p	oin / output voltage(-)	V_{GL}, V_{O-}	-5	-4	-3	V	No load
Miller clamp v	oltage	V_{CLAMP}	-	1.2	-	V	I_{CLAMP} =500mA, Guaranteed by design
Miller clamp ON threshold voltage		V _{CLPON}	-	V_{GL} +2	-	V	
Delay time	Turn ON time	t _{PON}	-	100	-	ns	
Delay tille	Turn OFF time	t _{POFF}	-	100	-	ns	
Dead time		t _{DEAD}	-	4.1	-	us	Half bridge mode

■Electrical Specification (Vin=24V, Vcc=5V.Ta=25°C, Unless otherwise specified)

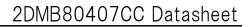
Protection

ltem	Symbol	Min	Тур	Max	Unit	Conditions · Note
DC/DC converter						
Overload protection	-	9.2	-	-	W	Auto recovery
Overheat protection	-	120	-	150	°C	Auto recovery, Internal temperature
Gate driver	-				-	
Output voltage(H) UVLO OFF voltage	$V_{\rm UVLOGHH}$	13.2	13.5	13.8	V	Guaranteed by design
Output voltage(H) UVLO ON voltage	V_{UVLOGHL}	12.2	12.5	12.8	V	Guaranteed by design
DESAT charge current	IDESAT	200	240	280	uA	Guaranteed by design
DESAT detection voltage	V_{DESAT}	6.0	6.35	7.0	V	Guaranteed by design
DESAT detection filter time	t _{DSTFIL}	-	300	-	ns	
DESAT detection time	t _{DSTOUT}	-	350	-	ns	
Alarm signal output L voltage	V _{ALML}	-	-	0.5	V	I _{ALM} =5mA
Alarm signal output time	t _{ALM}	-	550	-	ns	
Restart time	t _{restart}	-	110	-	ms	
Soft turn off duration	t _{sto}	-	4	-	us	



■Insulation

ltem	Specification	Conditions · Note	
Between Input-Output	•	•	
Dielectric withstand voltage	AC5000V	1min, Cutoff 2mA	
Insulation resistance	$100M\Omega$ or more	DC500V	
Partial discharge extinction volt.	1768Vpeak or more	According to EN50178/IEC 60270	
Common-mode transient immunity (CMTI)	70kV/us		
Minimum clearance distances	14mm		
Minimum creepage distances	14mm		
Between CH1-CH2	-	• •	
Dielectric withstand voltage	AC4000V	1min, Cutoff 2mA	
Insulation resistance	$100M\Omega$ or more	DC500V	
Partial discharge extinction volt.	1700Vpeak or more	According to EN50178/IEC 60270	
Minimum clearance distances	7mm		
Minimum creepage distances	12mm		





■Pin Function

·VIN+, VIN- (Power supply pin for DC/DC converter)

·VCC(Power supply pin for drive circuit)

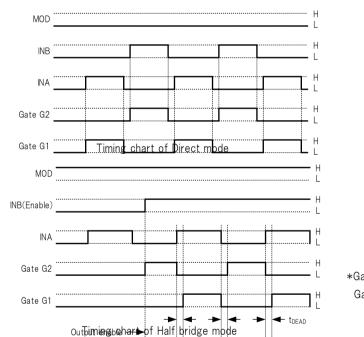
·GND(Ground pin for drive circuit)

•MOD, INA, INB(Mode switching pin, Control input pin)

The INA, INB and MOD pin is a pin used to determine output logic. Direct mode / Half bridge mode can be switched by MOD pin.

In Half bridge mode, it functions as INA: gate signal, INB: enable signal.

Mode	Gate G1 *	Gate G2 *	INA	INB	MOD
	L	Х	L	Х	L
Direct mode	Н	Х	Н	Х	L
Direct mode	Х	L	Х	L	L
	Х	Н	Х	Н	L
	L	L	Х	L	Н
Half bridge mode	L	Н	L	Н	Н
	Н	L	Н	Н	Н



*Gate G1:Gate output of CH1 side Gate G2:Gate output of CH2 side

 $\cdot \text{DTC1,2}(\text{Dead time adjustment pin})$

When half-bridge mode, this pin is adjust the dead time of gate output G1,G2

 $\cdot \texttt{RTC}(\texttt{Recovery time of protection circuit control pin})$

When abnormality occurs (UVLO, short circuit detected), this pin is used to adjust the recovery time.



\cdot ALM1,2(Alarm signal output pin)

When abnormality occurs (UVLO, short circuit detected), This pin outputs an alarm signal. (Open drain)

Status	ALM1,2
While in normal operation	Hi–Z
UVLO, When detecting short circuit	L

·MCL1,2(Miller clamp pin)

The MCL pin is a pin for preventing increase in gate voltage due to the miller current of the power device connected to Gate pin.

·ST01,2(Soft turn off pin)

The STO pin is a pin for gradually decrease gate voltage in operating desaturation protection.

STO pin connect to the gate pin though a resistance value higher than the resistance value connected to VGL 1 and 2.

·VGL1,2(Gate OFF side pin)

The VGL pin is a pin for gate drive of low signal. VGL pin connect to the gate pin through gate resistor of OFF side.

·VGH1,2(Gate ON side pin)

The VGH pin is a pin for gate drive of high signal. VGH pin connect to the gate pin through gate resistor of ON side.

·E/S1,2(Emitter/source pin)

 $\ensuremath{\mathsf{E}}/\ensuremath{\mathsf{S}}$ pin connect to the emitter / source of the power device.

·V01+,V02+,V01-,V02-(DC/DC converter output pin)

The VO+,VO2+,VO1-,VO2- pin is a output pin of built-in DC/DC converter. If necessary, connect a capacitor.

·DST1,2(Desaturation protection pin)

The DESAT pin is a pin used to detect desaturation. When the DESAT pin voltage exceeds V_{DESAT} , the DESAT function will be activated. This may cause the IC to malfunction in an open state. To avoid such trouble, short-circuit the DESAT pin to the E/S pin if the desaturation protection is not used. In order to prevent the wrong detection due to noise, the noise mask time $t_{DESATFIL}$ is set.

Description

1. Gate voltage rise prevention function (Miller clamp function)

If gate output Gx=L and the Miller clamp pin voltage < V_{CLPON} , the internal MOSFET of the miller clamp pin turns on.

Gate Gx	MCL	Internal MOSFET of the MCL pin
L	Less than $V_{ ext{CLPON}}$	ON
L	Not less than $V_{\mbox{\tiny CLPON}}$	OFF
Н	Х	OFF

2. Undervoltage Lockout (UVLO) function

The control circuit incorporates the undervoltage lockout (UVLO) function on the output voltage + sides. When the output voltage+ drops to the UVLO ON voltage, the gate ON/OFF side pin and the ALM pin both will output the "L" signal. When the output voltage+ rises to the UVLO OFF voltage, these pins will be reset.



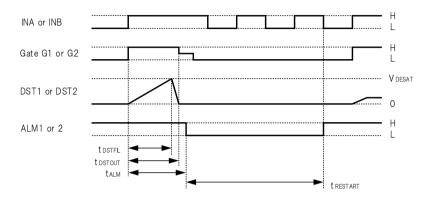
3. Short circuit protection function, Soft turn-off function

When the DESAT pin voltage exceeds V_{DESAT} , the short circuit protection function will be activated. When the short circuit protection function is activated, the gate ON/OFF side pin will be set to the "Hi-Z" level,

and then the ALM pin voltage to the "L" level.

Also, soft turn-off function works to reduce collector/drain voltage surge due to short circuit current.

Short-circuit protection is canceled automatically after an abnormal condition restart time and when the input signal is "L" level.



Timing chart of short circuit protection function

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■Reliability

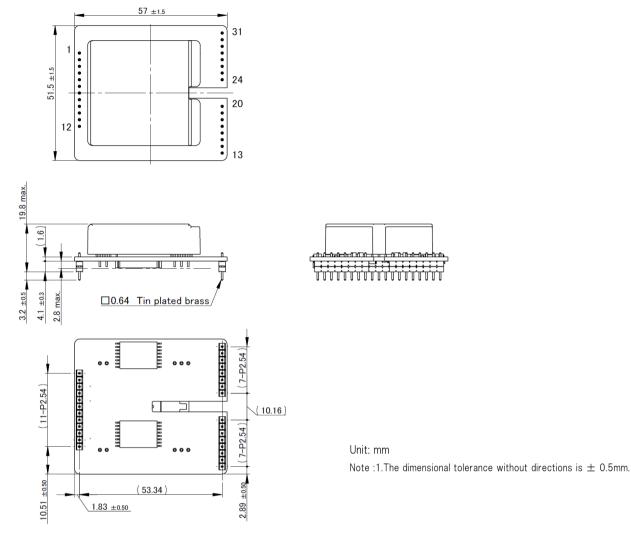
Item	Test condition and acceptance criterion			
Exposure in high temperature	IEC60068-2-2:2007: Test: Bb, 90°C, 240H, %			
Exposure in low temperature	IEC60068-2-1:2007: Test: Ab40°C. 240H. X			
Exposure in high temperature and high humidity	IEC60068−2−78:2012−10, 60°C, 90~95%RH, 240H, ※			
Thermal shock	IEC60068-2-14:2009-01: Test: Na, -40°C/30min to 100°C/30min, 500cycles, %			
Low temperature operation	IEC60068-2-1:2007: Test: Ae, Input voltage: DC24V, Output current: Rated Load			
	-40°C, 240H, ※			
High temperature operation	IEC60068-2-2:2007: Test: Be, Input voltage: DC24V, Output current: Rated Load			
	85°C, 240H,			
high temperature	IEC60068-2-78:2012-10, Input voltage: DC24V, Output current: Rated Load			
and high humidity operation	85°C, 85%RH, 240H, 💥			
Vibration	IEC 60068-2-6:2007-12, Frequency range: 10 to 55Hz, Sweep rate: 1.0oct/min,			
	Displacement amplitude: \pm 0.75mm, Test duration: 120min, Axis: X,Y and Z, $$ $$ $$ $$ $$ $$			
	IEC 60068-2-6:2007-12, Frequency range: 5 to 200Hz, Sweep rate: 1.0oct/min,			
	Cross-over frequency: 8.4Hz, , Displacement amplitude(5 to 8,4Hz): \pm 3.5mm,			
	Acceleration amplitude(8.4 to 200Hz):1G, Test duration: 20sweeps, Axis: X, Y and Z, 💥			
Impact	IEC 60068-2-27:2008-02, Pulse shape: Half-sine, Corresponding duration: 11ms,			
	Peak acceleration: 50G, Number of shocks:3, Axis: \pm X, Y and Z, $$ $\!$ $\!$ $\!$ $\!$ $\!$ $\!$ $\!$ $\!$ $\!$ $\!$			
	IEC 60068-2-27:2008-02, Pulse shape: Half-sine, Corresponding duration: 6ms,			
	Peak acceleration: 15G, Number of shocks:100, Axis: \pm X, Y and Z, $$ $$ $$ $$ $$ $$			
Solderability	Sample shall be dipped into the solution of Methanol and Rosin			
	(having 75% Methanol and having 25% Rosin by weight measuring)			
	and shall be dipped into the solder bath having the solder Sn-3Ag-0.5Cu			
	of $250\pm5^\circ$ C to the position to 3mm from the end of terminal for 3.0 ± 0.5 seconds,			
	and pulled up. After above treatment, the sample shall be covered by solder uniformly			
	at more than 75% of circumference and shall not show any unusual appearance.			
Resistance to soldering heat	Sample shall be dipped into the solution of Methanol and Rosin			
	(having 75% Methanol and having 25% Rosin by weight measuring)			
	and shall be dipped into the solder bath having the solder Sn-3Ag-0.5Cu			
	of 260 $\pm5^\circ$ C to the position to 3mm from the end of terminal for 10.0 \pm 0.5			
	seconds, and pulled up. After that sample shall be replace in normal ambient			
	for 1 \sim 2 hours and shall not show any unusual appearance.			

%After each test, exposure at room temperature and humidity condition for 24 hours.

There shall be no abnormality on the electrical specification and appearance.



■Outline Dimensional Drawing





45g(TYP)

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Recommended Soldering Condition

 $\cdot \mathsf{Flow}$ soldering condition

255±3°C Less than 3sec
 Temperature of preheating 110°C~130°C
 End temperature of preheating 110°C±10°C
 360°C(MAX) Less than 3sec

 $\cdot \, \text{Soldering condition of hand work}$

■Storage Conditions

ltem	Min	Max	Unit	Conditions · Note
Storage temperature	-25	60	°C	A packing state

%If you want to use past the long period there is a concern that the solder non-wetting by terminal oxidation to occur. Therefore, please use from taking enough tests.

■Usage Cautions

- Always mount fuse on the plus side of input for ensuring safety because the fuse is not built-in the product.
 Please select the fuse considering conditions such as steady current, inrush current, and ambient temperature.
 When using a fuse having large rated current or high capacity input electrolytic condenser, by combining another converter and input line and input electrolytic condenser, fuse may not blow off in the case of abnormality.
 Do not combine high voltage line and fuse.
- Make sure the rise/fall time of the input signal is 500ns or less.
- This product has DESAT protection for arm short circuit and load short circuit protection.
 However, even if this protection works, the IGBT may be damaged if abnormally high current occurs due to IGBT's characteristics variations or the load short-circuit mode during parallel operation.
 To ensure safety, be sure to check the short-circuit current at the unit in which this product is integrated, and evaluate whether it can protect under the condition that there is no damage to the IGBT.





Important Notice

- This information and product are subject to change without prior notice for the purpose of improvements, etc. Ensure that you are in possession of the most up-to-date information when using this product.
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- TAMURA Corporation constantly strives to improve quality and reliability, but malfunction or failures are bound to occur with some probability in power products. To ensure that failures do not cause accidents resulting in injury or death, fire accidents, social damage, and so on, you are to thoroughly verify the safety of their designs in devices and/or systems, at your own responsibility.
- This product is intended for use in consumer electronics (electric home appliances, business equipment, Information equipment, communication terminal equipment, measuring devices, and so on.) If considering use of this product in equipment or devices that require high reliability (medical devices, transportation equipment, traffic signal control equipment, fire and crime prevention equipment, aeronautics and space devices, nuclear power control, fuel control, in-vehicle equipment, safety devices, and so on), please consult a TAMURA sales representative in advance. Do not use this product for such applications without written permission from TAMURA Corporation.
- This product is intended for use in environments where consumer electronics are commonly used. It is not designed for use in special environments such as listed below, and if such use is considered,
 - you are to perform thorough safety and reliability checks at your own responsibility.
 - Use in liquids such as water, oil, chemical solutions, or organic solvents, and use in locations where the product will be exposed to such liquids.
 - Use that involves exposure to direct sunlight, outdoor exposure, or dusty conditions.
 - Use in locations where corrosive gases such as salt air, C12, H2S, NH3, SO2, or NO2, are present.
 - Use in environments with strong static electricity or electromagnetic radiation.
 - Use that involves placing inflammable material next to the product.
 - Use of this product either sealed with a resin filling or coated with resin.
 - Use of water or a water soluble detergent for flux cleaning.
 - · Use in locations where condensation is liable to occur.
- This product is not designed to resist radiation.
- This product is not designed to be connected in series or parallel.
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